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BIBDATASHEET

Bib Data Sheet

CONFIRMATION NO. 2253

SERIAL NUMBE 10/608,605	ER	FILING DATE 06/27/2003 RULE	-	:Lass 257	GROUP ART 2811	UNIT	D	ATTORNEY OCKET NO. 70030259-1		
APPLICANTS										
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Kee Yean Ng, Penang, MALAYSIA; Yew Cheong Kuan, Penang, MALAYSIA;Gin Ghee Tan, Penang, MALAYSIA; Cheng Why Tan, Penang, MALAYSIA;										
** CONTINUING DATA **********************************										
** FOREIGN APPLICATIONS ************************************										
IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 09/17/2003										
Foreign Priority claimed 35 USC 119 (a-d) cond	, , , , , , , , , , , , , , , , , , ,		Allowarce	STATE OR	SHEETS		TAL	INDEPENDENT		
met Verified and Acknowledged	Examiner's Signature Initials			COUNTRY MALAYSIA	DRAWING 8	5	IMS 0	CLAIMS 2		
ADDRESS AGILENT TECHNOLOGIES, INC. Legal Department, DL429 Intellectual Property Administration P.O. Box 7599 Loveland, CO 80537-0599										
TITLE Packaging device for semiconductor die, semiconductor device incorporating same and method of making same										
							All Fees			
						1.16 Fees (Filing)				
FILING FEE	EES	: Authority has been giv	oer OSIT ACCOUN		☐ 1.17 Fees (Processing Ext. of time)					
RECEIVED	No to charge/credit DEPOSIT ACCOUNT No for following:				□ 1.18	1.18 Fees (Issue)				
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